

FEATURES

- High Current Transfer Ratios
at 5 mA: 50–600%
at 1 mA: 60% typical (>13)
- Low CTR Degradation
- Good CTR Linearity Depending on Forward Current
- Isolation Test Voltage, 5300 VAC_{RMS}
- High Collector-Emitter Voltage, V_{CEO}=70 V
- Low Saturation Voltage
- Fast Switching Times
- Field-Effect Stable by TRIOS (Transparent IOn Shield)
- Temperature Stable
- Low Coupling Capacitance
- End-Stackable, .100" (2.54 mm) Spacing
- High Common-Mode Interference Immunity (Unconnected Base)
- Underwriters Lab File #52744
- VDE 0884 Available with Option 1
SMD Option – See SFH6106/16/56 Data Sheet

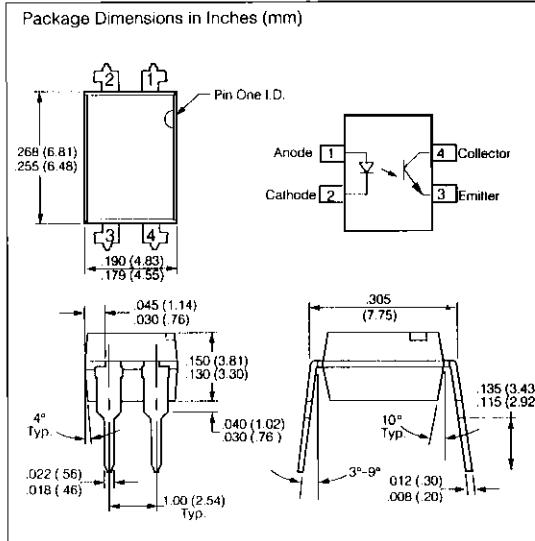
DESCRIPTION

The SFH615AA/AGB features a high current transfer ratio, low coupling capacitance and high isolation voltage. These couplers have a GaAs infrared emitting diode emitter, which is optically coupled to a silicon planar phototransistor detector, and is incorporated in a plastic DIP-4 package.

The coupling devices are designed for signal transmission between two electrically separated circuits.

The couplers are end-stackable with 2.54 mm spacing.

Creepage and clearance distances of >8 mm are achieved with option 6. This version complies with IEC 950 (DIN VDE 0805) for reinforced insulation up to an operation voltage of 400 V_{RMS} or DC.

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Maximum Ratings**Emitter**

Reverse Voltage	6 V
DC Forward Current60 mA
Surge Forward Current ($t_p \leq 10 \mu s$)	2.5 A
Total Power Dissipation	100 mW

Detector

Collector-Emitter Voltage	70 V
Emitter-Collector Voltage	7 V
Collector Current50 mA
Collector Current ($t_p \leq 1 ms$)	100 mA

Package

Isolation Test Voltage between Emitter and Detector, refer to Climate DIN 40046, part 2, Nov. 74	5300 VAC _{RMS}
Creepage.....	≥7 mm
Clearance.....	≥7 mm
Insulation Thickness between Emitter and Detector	≥20.4 mm
Comparative Tracking Index per DIN IEC 112/VDEO 303, part 1	≥175
Isolation Resistance	
$V_{IO}=500 V, T_A=25^\circ C$	≥10 ¹² Ω
$V_{IO}=500 V, T_A=100^\circ C$	≥10 ¹¹ Ω
Storage Temperature Range	-55 to +150°C
Ambient Temperature Range.....	-55 to +100°C
Junction Temperature	100°C
Soldering Temperature (max. 10 s. Dip Soldering Distance to Seating Plane ≥1.5 mm)	260°C

Specifications subject to change.

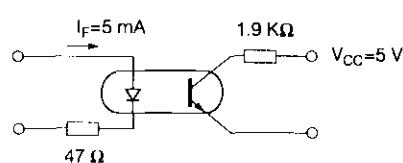
Characteristics ($T_A=25^\circ\text{C}$)

Description	Symbol		Unit	Condition
Emitter (IR GaAs)				
Forward Voltage	V_F	1.25 (≤ 1.65)	V	$I_F=60 \text{ mA}$
Reverse Current	I_R	0.01 (≤ 10)	μA	$V_R=6 \text{ V}$
Capacitance	C_0	13	pF	$V_{CE}=0 \text{ V}, f=1 \text{ MHz}$
Thermal Resistance	R_{ThJA}	750	K/W	
Detector (Si Phototransistor)				
Capacitance	C_{CE}	5.2	pF	$V_{CE}=5 \text{ V}, f=1 \text{ MHz}$
Thermal Resistance	R_{ThJA}	500	K/W	
Package				
Collector-Emitter Saturation Voltage	V_{CESAT}	0.25 (≤ 0.4)	V	$I_F=10 \text{ mA}, I_C=2.5 \text{ mA}$
Coupling Capacitance	C_C	0.4	pF	

Current Transfer Ratio (I_C/I_F at $V_{CE}=5 \text{ V}$) and Collector-Emitter Leakage Current

Description	AA	AGB	
$I_C/I_F (I_F=5 \text{ mA})$	50–600	100–600	%
Collector-Emitter Leakage Current, I_{CEO} $V_{CE}=10 \text{ V}$	10 (≤ 100)	10 (≤ 100)	nA

Switching Operation (with saturation)



		$I_F=5 \text{ mA}$	
Turn-on Time	t_{ON}	2.0	μs
Turn-off Time	t_{OFF}	25	μs

Figure 1. Current transfer ratio (typ.) vs. temperature
 $I_F=10 \text{ mA}$, $V_{CE}=0.5 \text{ V}$

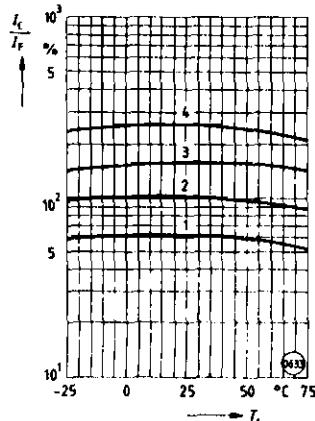


Figure 4. Transistor capacitance (typ.) vs. collector-emitter voltage
 $T_A=25^\circ\text{C}$, $f=1 \text{ MHz}$

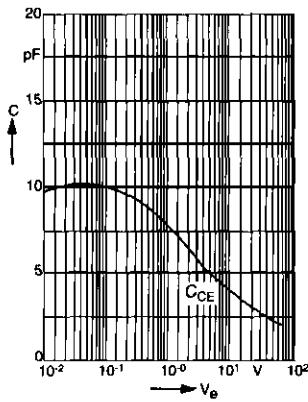


Figure 7. Permissible diode forward current vs. ambient temp.

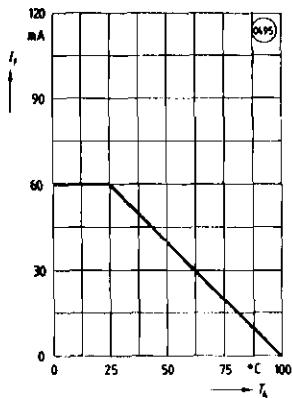


Figure 2. Output characteristics (typ.)
 Collector current vs. collector-emitter voltage $T_A=25^\circ\text{C}$

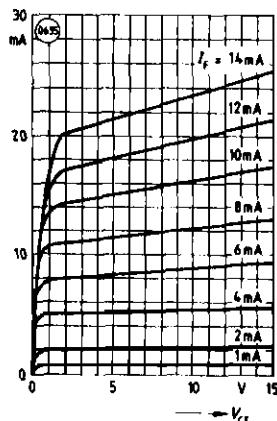


Figure 5. Permissible pulse handling capability. Fwd. current vs. pulse width
 Pulse cycle D-parameter, $T_A=25^\circ\text{C}$

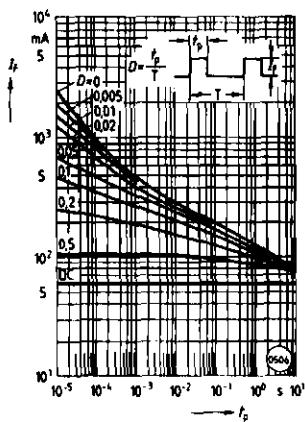


Figure 3. Diode forward voltage (typ.) vs. forward current

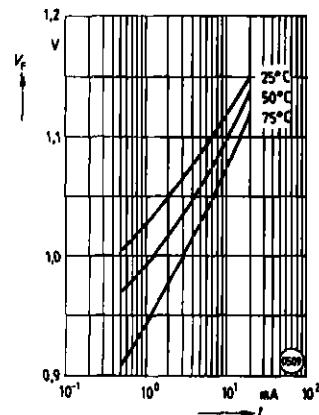
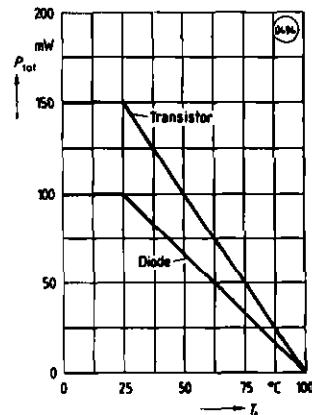


Figure 6. Permissible power dissipation vs. ambient temp.



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